International Application No. PCT/JP2004/017121 I.A. Filed November 11, 2004 Applicant: Hiroshi FUKSHIMA et al. Attorney Docket No. P29715 Title: A METHOD FOR PRODUCING A LIGHT-EMITTING DEVICE REPLACEMENT SHEET

FIG.5 START OF PRODUCTION OF LIGHT-EMITTING DEVICE PROVIDED WITH MINUTE EMBOSSED STRUCTURES FOR PREVENTING MULTIPLE REFLECTION S₁ LAYER SEMICONDUCTOR LAYER ON TRANSPARENT CRYSTAL SUBSTRATE (FORM LIGHT-EMITTING LAYER) S2 TRANSFER LAYER FORMING STEP (#10) ARRANGEMENT OF TRANSFER-LAYER MATERIAL (#11) CASE 1: ARRANGE TRANSFER LAYER ON TRANSPARENT CRYSTAL SUBSTRATE (#12) CASE 2: ARRANGE ON SEMICONDUCTOR LATER (#13) CASE 3: SEPARATE TRANSPARENT CRYSTAL SUBSTRATE AND ARRANGE TRANSFER LAYER ON SEMICONDUCTOR LAYER (SUBSTRATE BEARING LAYER IS FORMED ON SEMICONDUCTOR LAYER AS PREPROCESSING) (#20) SOFTENING OF TRANSFER-LAYER MATERIAL (#21) IN THE CASE OF THERMOPLASTIC MATERIAL: SOFTENING BY SUPPLYING ENERGY (HEAT, LIGHT) (#22) IN THE CASE OF SOFT MATERIAL: SOFTENING IS COMPLETED BY ARRANGING THE MATERIAL **S3** TRANSFERRING STEP (#30) ARRANGE MOLD FORMED WITH MINUTE EMBOSSED STRUCTURES ON TRANSFER-LAYER MATERIAL (#40) PRESS MOLD AGAINST SOFTENED LAYER TO TRANSFER MINUTE EMBOSSED STRUCTURES (#50) SOLIDIFY SOFTENED LAYER AND FIX MINUTE EMBOSSED STRUCTURES (#51) IN THE CASE OF THERMOPLASTIC MATERIAL: SOLIDIFICATION AFTER COOLING (#52) IN THE CASE OF THERMOSETTING MATERIAL: SOLIDIFICATION AFTER HEATING (#53) IN THE CASE OF LIGHT-SETTING MATERIAL: SOLIDIFICATION BY IRRADIATION WITH LASER BEAM (#60) SEPARATE MOLD FROM TRANSFER-LAYER MATERIAL **S4** MULTIPLE-REFLECTION PREVENTING STRUCTURE FORMING STEP (#70) CASE 1: ETCHING IS CARRIED OUT FROM THE UPPER SURFACE OF TRANSFER -LAYER MATERIAL HAVING THE MINUTE EMBOSSED STRUCTURES TRANSFERRED THERETO UP TO BACKING LAYER TO FORM MINUTE EMBOSSED STRUCTURES IN BACKING LAYER (#70) CASE 2: MINUTE EMBOSSED STRUCTURES TRANSFERRED TO AND FIXED IN TRANSFER LAYER ARE USED AS MINUTE EMBOSSED STRUCTURES AS THEY ARE **S**5 CUT SUBSTRATE INTO INDIVIDUAL CHIPS OF LIGHT-EMITTING DEVICES

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